

Notice of References Cited	Application/Control No. 10/764,608		Applicant(s)/Patent Under Reexamination LIU, AI-SEN	
	Examiner C. J. Arbes		Art Unit 3729	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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X	B	US-6,444,568 B1	09-2002	Sundararajan et al.	438/627
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	M	US-			

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NON-PATENT DOCUMENTS

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X	U	Low Temperature Metal-Organic Chemical Vapor Deposition of Tungsten Nitride as Diffusion Barrier for Copper Metallization b J.E. Kelsey et al J. Vacuum Science & Technology B Vol. 17, No. 3 pp 1101-4 May-June1999.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.